



AFJ TFW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Kiyokazu
MORIIZUMI et al.**

Group Art Unit: **2818**

Serial Number: **10/784,740**

Examiner: **David Nhu**

Filed: **February 24, 2004**

Confirmation No.: **2459**

For: **MOUNTED CIRCUIT SUBSTRATE AND METHOD FOR
FABRICATING THE SAME FOR SURFACE LAYER PADS THAT
CAN WITHSTAND PAD EROSION BY MOLTEN SOLDER
APPLIED OVER A PLURALITY OF TIMES**

Attorney Docket Number: **001480A**

Customer Number: **38834**

RESPONSE AFTER FINAL

MAILSTOP: AF

Commissioner for Patents

P. O. Box 1450

Alexandria, VA 22313-1450

September 29, 2005

Sir:

This paper is being filed in response to the Quale Action dated August 8, 2005.

Amendments to the Claims are reflected in the listing of claims that begins on page 2 of
this paper.

Remarks/Arguments begin on page 5 of this paper.